

FEATURES		CAPABILITIES	REMARKS
<i>N° of layers</i>		1-40 Layers *	
<i>Board Materials</i>		FR4 - Normal TG (also halogen free) FR4 - High TG (also halogen free) PTFE laminates Ceramic particle filled laminates Aluminium Hybrid laminating	there is a wide range of different types of laminate/prepreg materials from different suppliers
<i>PCB Buildings Technology</i>		Blind&Buried Vias, Backplane, HDI, High Multi-Layer, Backdrill, Heavy Copper Power Pcb/ Metal Substrate, Copper or Resin Filling, Impedance controlled	RIGID-FLEX and FLEX Building technology
<i>Maximum Finished PCB size</i>	<i>Single layer & Double layer</i>	584.2 x 889 mm (23x35")	
	<i>Multilayer</i>	571.5 x 851 mm (22.5x33.5")	
	<i>Backplane technology</i>	571.5 x 1143 mm (22.5x45") *	
<i>PCB thickness</i>	<i>Single layer - 2 layers</i>	0.20 - 7.00 mm (8 - 275.6 mil)	H.A.L. 0.60 - 4.00 mm (23.6 - 157.5 mil); ENIG 0.20 - 7.00 mm (8 - 275.6 mil); Immersion Tin/Silver 0.40 - 5.00 mm (15.7 - 196.9 mil); Hard Gold 0.20 - 5.00 mm (8 - 196.9 mil)
	<i>Multilayers</i>	0.40 - 7.00 mm (15.7 - 275.6 mil)	
	<i>Tolerance</i>	≤ 1.00 mm: ± 0.1 mm (≤ 40 mil: ± 4 mil) ≥ 1.00 mm: ± 10 % (≥ 40 mil)	
<i>Base Copper thickness</i>		1/3 Oz, 1/2 Oz, 1 to 10 Oz	1 Oz = 35 µm
<i>Surface Finish</i>		H.A.L. lead free (RoHS - Pb free), H.A.L. with Pb, Immersion gold or ENIG (RoHS) Immersion Tin, Immersion Silver, Hard Gold, ENEPIG, Peelable solder mask Hybrid Surface finish	
<i>Solder Mask</i>	<i>Colors</i>	Green matte/glossy, Yellow, Black, Blue, Red, White, Purple	
	<i>Minimum width</i>	 Base Copper ≤ 1 Oz (35 µm): 0.1 mm (4 mil) for Green, 0.13 mm (5 mil) other colors Base Copper 2 Oz (70 µm) - 4 Oz (140 µm): 0.15 mm (6 mil)	Minimum 0.2 mm (8 mil) between copper areas
<i>Silkscreen</i>	<i>Colors</i>	White, Yellow, Black	
<i>Finished Mechanical Hole Size PTH</i>		0.1 - 6.2 mm (4 - 244 mil)	
<i>Laser Drilling Size</i>		0.1 - 0.15 mm (4 - 6 mil) *	
<i>HDI</i>		4 + N + 4 *	
<i>Aspect Ratio (Mechanical THT)</i>		12:1	20:1 for Hole diameter > 0.20 mm (8 mil)
<i>Minimum Track Width/Space</i>		76 - 76 µm (3 / 3 mil) on internal layers *	Using copper thickness 1/3 Oz (12 µm), 1/2 Oz (17.5 µm)
		76 - 76 µm (3 / 3 mil) on external layers *	Using copper thickness 1/3 Oz (12 µm)
<i>Minimum Pad Size for Mechanical Drillings</i>		0.4 mm (16 mil) *	Using copper thickness ≤ 1/2 Oz (17.5 µm) and 0.2 mm (8 mil) drilling size
<i>Other Special Processes</i>		Impedance Control (tolerance: ± 10 %) Blind&Buried Vias Filled holes Pressfit holes (tolerance: ± 50 µm (± 2 mil)) Z-axis routing Gold Finger Counter bore and Counter sink Chamfering/Beveling	on special products also ± 5 %

* Different solutions are available on demand